



17th EUROPEAN MICROELECTRONICS and PACKAGING CONFERENCE & EXHIBITION



International Microelectronics
And Packaging Society
Italian Chapter

EMPC 2009

June 15th -18th, 2009 - Rimini - Italy

www.empc2009.org

CALL FOR PAPERS

Deadline for submission: December 31st 2008

STEERING COMMITTEE

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Roberto May

Co-chair:

**Tino Taddei,
Giovanni Delrosso**

Treasurer:

Antonello Ciappesoni

Technical programme:

**Carlo Cognetti,
Roberto Dell'Acqua**

Professional Development

Courses:

Alessandro Gandelli

Exhibition:

Luigi Calligarich

Marketing:

Janmario Reina

Main Sponsor:



STMicroelectronics



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

AMES

Associazione Microelettronica
Elettronica, Semiconduttori

The aim of IMAPS is to take to Rimini, one of the most renowned bathing resort towns in Italy, the best of Microelectronics and Packaging, thus offering a top quality coverage of technological innovation related to microelectronic packaging and interconnection technologies. The four day Conference and Exhibition will be held from 15th to 18th June 2009 at Palacongressi in Rimini. It will be complemented by Advanced Professional Courses and by poster sessions.

You are cordially invited to submit a paper on Microelectronics Technologies, for oral or poster presentation at the Conference, on the following topics:

ADVANCED PACKAGING:

- Single Chip and Multi Chip Packaging, Wafer Level Packaging, 3D-WLP, 3D-IC, SIP, SOP and other System Integration Technologies;
- Embedded Passives on Wafers and Substrates;
- High Frequency and High Power Packaging;
- LTCC Ceramics Technologies;
- PCB and BGA Substrates Design and Technologies, Laminates, Micro-Vias and Build-Up Technologies, Flex, MID.

INTERCONNECTION TECHNOLOGIES:

- Thick and Thin Film Technologies;
- Wire Bonding, Bumping, Flip Chip Bonding;
- Cu/Low-k Wafers, Through Silicon Vias;
- Lead-Free Soldering and Adhesive Joining.

MORE THAN MOORE:

- MEMS Packaging: MEMS Based Sensors and Actuators Packaging, RF-MEMS, Optical MEMS and Bio-MEMS;
- Optoelectronics: Power LED Packaging and Light Guiding, Packaging of Optoelectronic Modules suitable for Gb/s Fiber Optic Communication;
- Solar Energy (Photovoltaics): Packaging Design to improve Efficiency of Photovoltaic modules Reliability and Qualification Approaches;
- Nano Technologies: Smart Materials, Interconnections, Nano-Scale Packaging;
- Medical Electronics: Applications, Design, Development, Manufacturing that comply with complex and demanding regulations and market requirements.

POWER ELECTRONICS:

Application in Consumer, Telecom, Automotive, Wearable, Space and Defence.

MANUFACTURING TECHNOLOGIES AND MATERIALS:

- Process Development, New Equipment, Yield Improvement, Cost and Cycle Time Reduction, Green Manufacturing;
- Adhesives, Encapsulants, Underfills, Moulding Compounds, Lead-Free Solder Alloys, Halogen Free Materials, Dielectrics and Ceramics.

MODELLING

- Electrical Modelling and Signal Integrity: Time and Frequency Domain Analysis of Interconnection and Packaging Technologies;
- Thermal Characterisation and Cooling Solutions: Modelling and Simulation Methodology for Characterisation of Advanced Packaging, Modules and Systems, Novel Cooling Techniques;
- Mechanical Modelling and Structural Integrity: Thermo-Mechanical Stress Analysis, Vibration and Shock Tests;
- Quality and Reliability: Component, Board and System Level Reliability Assessment, Failure Analysis, Interfacial Adhesion and Accelerated Testing Methods.

EMPC 2009

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15th - 18th June 2009, Rimini - Italy

Organizing Secretariat: Pragma Congressi - C.so Mazzini, 14 - 27100 Pavia - Italy
Tel. +39 0382 309579 - Fax +39 0382 304892 - E-mail: segreteria@empc2009.org

INFORMATION ON THE CONFERENCE

CALL FOR PAPERS

If you wish to present a paper for oral or poster presentation at the 17th European Microelectronics and Packaging Conference please complete the form below and send it, together with you summary, to the Conference Secretariat before **31st december 2008**. The summary must be between 200 to 300 words and clearly describe the nature, scope, content, organization, key points and significance of the proposed paper. The paper must present works and results not previously published. Paper selection will be announced by February 28th 2009. The Technical Programme Committee's decision is final.

Submission of an abstract represents a commitment to send a final manuscript by April 15th 2009. It also represents a commitment to either attend the Conference or to send a knowledgeable substitute who can present the paper, as well as answer pertinent questions. Speakers will be admitted to the Conference at a much reduced fee. The conference language is English. Please send your abstract to: **abstracts@empc2009.org**

EXHIBITION:

Throughout the Conference there will be a major exhibition that will allow the conference attendants to meet and discuss with:

- Material Suppliers
- Manufacturers of equipment and products for Hybrid Microelectronics and MCMs
- Component Suppliers
- Manufacturers of Hybrids and Packages
- Suppliers of Test and Analysis Equipment and Services
- Academia and R&D Laboratory People

The exhibition, in line with the suggestions of previous participants, will be held under the following conditions:

1. Exhibition area and conference main rooms on the same floor
2. Entry to the Conference sessions through the exhibition area
3. A special "Exhibition forum" in parallel with the conference sessions enabling exhibitors to illustrate the technical novelties of their products.

SPECIAL SESSIONS AND ADVANCED PROFESSIONAL COURSES

In addition to the topics on the front page, there will be special sessions with appealing papers presented by eminent invited speakers from all over the world. Moreover there will be the possibility to attend professional courses on advanced topics in Microelectronics.

Please indicate on the attached form your preferred special course subject



Conference Web Site:

www.empc2009.org

Conference Secretariat Address

PRAGMA CONGRESSI
C.so Mazzini, 14 - 27100 Pavia - Italy
Tel. +39 0382 309579 - Fax +39 0382 304892
E-mail: segreteria@empc2009.org

17th EUROPEAN MICROELECTRONICS and PACKAGING - CONFERENCE & EXHIBITION EMPC 2009

Please complete this form and e-mail or fax it to the above address

FIRST NAME FAMILY NAME

COMPANY ADDRESS

CITY ZIP CODE COUNTRY

TEL. FAX E-mail:

I intend to submit a paper

I am interested in attending the Conference

I am interested in exhibiting

I am interested in attending a professional course